

L Number	Hits	Search Text	DB	Time stamp
1	5198	((leadframe lead) and (flipchip (flip adj chip)))	USPAT; EPO; JPO	2003/06/04 13:03
2	1167	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) with (polymer polymeric polyimide plastic))	USPAT; EPO; JPO	2003/06/04 13:06
3	921	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide plastic))	USPAT; EPO; JPO	2003/06/04 13:15
4	198	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide plastic)) and (underfill\$2 (under adj fill\$2))	USPAT; US-PGPUB; JPO; DERWENT	2003/06/04 13:15
5	278	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide))	USPAT; EPO; JPO	2003/06/04 13:15
6	88	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide)) and (underfill\$2 (under adj fill\$2))	USPAT; US-PGPUB; JPO; DERWENT	2003/06/04 14:51
7	31	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide)) and (underfill\$2 (under adj fill\$2)) and pitch	USPAT; US-PGPUB; JPO; DERWENT	2003/06/04 15:16
8	100	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide)) and pitch	USPAT; US-PGPUB; JPO; DERWENT	2003/06/04 15:16
9	69	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide)) and pitch) not (((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide))) and (underfill\$2 (under adj fill\$2)) and pitch	USPAT; US-PGPUB; JPO; DERWENT	2003/06/04 15:16
10	16	((leadframe lead) and (flipchip (flip adj chip))) and ((encapsulant encapsulated encapsulating sealing sealed molding molded) near3 (polymer polymeric polyimide)) and (lead near3 pitch)	USPAT; US-PGPUB; JPO; DERWENT	2003/06/04 15:17

I. Number	Hits	Search Text	DB	Time stamp
41	17	("3691289" "3765590" "4109096" "4183135" "4312926" "4657170" "4999699" "5034349" "5080279" "5146310" "5289344" "6034422" "6160312" "6184573" "6191952" "6232148" "6258622").PN.	USPAT	2003/06/05 09:15
42	1	6160312.URPN.	USPAT	2003/06/05 09:17
45	15	("4774630" "5222014" "5237434" "5266912" "5454160" "5491612" "5559305" "5565706" "5568574" "5652462" "5677567" "5801433" "5869895" "5907166" "6043557").PN.	USPAT	2003/06/05 09:17
70	13	6140144.URPN.	USPAT	2003/06/05 09:22
71	13	6140144.URPN.	USPAT	2003/06/05 09:23
72	10	("4763098" "4838089" "5209122" "5285690" "5591679" "5600071" "5646072" "5721446" "5889211" "5994161").PN.	USPAT	2003/06/05 09:24
73	15	6108210.URPN.	USPAT	2003/06/05 09:24
74	5	("5528083" "5801447" "6108210" "6121690" "6365436").PN.	USPAT	2003/06/05 09:25
77	0	6462427.URPN.	USPAT	2003/06/05 09:26
108	10	5895229.URPN.	USPAT	2003/06/05 09:31
109	10	5895229.URPN.	USPAT	2003/06/05 09:32
110	7	("5089440" "5218759" "5285352" "5302849" "5371404" "5682066" "5804881").PN.	USPAT	2003/06/05 09:32

L Number	Hits	Search Text	DB	Time stamp
1	0	5450283.pn	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:12
2	2	5450283.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:12
3	2	5784261.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:12
4	2	5895229.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:13
5	2	5981314.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:13
6	2	5998243.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:16
7	2	6038136.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:17
8	2	6049122.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:17
9	2	6071755.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:17
10	2	6081997.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:17
11	2	6344162.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:17
12	0	us20020109241	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:18
13	2	"20020109241"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:18
14	2	"20020114144"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:18
15	24	5450283.pn 5450283.pn. 5784261.pn. 5895229.pn. 5981314.pn. 5998243.pn. 6038136.pn. 6049122.pn. 6071755.pn. 6081997.pn. 6344162.pn. "20020109241" "20020114144"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/04 09:18